

	Hits	Search Text	DBs
2	3	((substrate or wafer) same (barrier or layer or coat\$4 or film) same (polyphenol\$4 near6 polymer\$4) same (resist or photoresist or photosensitive)) and (expos\$4 or irradiat\$4 or illuminat\$4) and develop\$4 and (etch\$4 or remov\$4) and (plat\$4 or electroplat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
3	1	((substrate or wafer) same (barrier or layer or coat\$4 or film) same ((polyphenol\$4 near6 polymer\$4) or novolac) same (resist or photoresist or photosensitive) same (azo near9 dye) same (repeat\$6 near9 monomer\$3)) and (expos\$4 or irradiat\$4 or illuminat\$4) and develop\$4 and (etch\$4 or remov\$4) and (plat\$4 or electroplat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
4	6	((substrate or wafer) same (barrier or layer or coat\$4 or film) same ((polyphenol\$4 near6 polymer\$4) or novolac) same (resist or photoresist or photosensitive)) and (expos\$4 or irradiat\$4 or illuminat\$4) and develop\$4 and (etch\$4 or remov\$4) and (plat\$4 or electroplat\$4) and ((phenolic near9 polymer\$7) same (monomer\$5 near9 unit))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
5	1	((substrate or wafer) same (barrier or layer or coat\$4 or film) same ((polyphenol\$4 near6 polymer\$4) or novolac or (poly near5 hydroxy near5 styrene)) same (resist or photoresist or photosensitive) same (((azo near9 dye) same monomer\$3) or poly\$3hydroxy\$4styrene)) and (expos\$4 or irradiat\$4 or illuminat\$4) and develop\$4 and (etch\$4 or remov\$4) and (plat\$4 or electroplat\$4) and undercut	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
6	3	((substrate or wafer) same (barrier or layer or coat\$4 or film) same ((polyphenol\$4 near6 polymer\$4) or novolac) same (resist or photoresist or photosensitive)) and (expos\$4 or irradiat\$4 or illuminat\$4) and develop\$4 and (etch\$4 or remov\$4) and (plat\$4 or electroplat\$4) and ((eliminat\$4 or remov\$4 or reduc\$5) near14 undercut\$3) and ((resist or photoresist) same (negative or positive))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
7	14	((substrate or wafer or device or workpiece) same (barrier or layer or coat\$4 or film) same (polyphenol\$6 or novolac or (poly near5 hydroxy near6 styrene)) same (resist or photoresist or photosensitive)) and (expos\$4 or irradiat\$4 or illuminat\$4) and develop\$4 and (etch\$4 or remov\$4) and ((plat\$4 or electroplat\$4) same sputter\$5) and undercut\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
8	2	((substrate or wafer or device or workpiece) same (barrier or layer or coat\$4 or film) same (polyphenol\$6 or novolac or (poly near5 hydroxy near6 styrene)) same (resist or photoresist or photosensitive)) and ((plat\$4 or electroplat\$4) same sputter\$5 same undercut\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
9	9	((plat\$4 or electroplat\$4) same replac\$5 same sputter\$5) and ((photoresist or resist or photosensitive) same undercut\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
10	3	((plat\$4 or electroplat\$4) near14 (substitut\$4 or replac\$5 or alternative) near14 sputter\$5) and ((photoresist or resist or photosensitive) same undercut\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
11	2	"20010005741"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
12	30	(antireflect\$4 same (polyphenol\$6 or novolac or (poly near5 hydroxy near6 styrene)) same (resist or photoresist or photosensitive))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
13	127	((plat\$4 or electroplat\$4) same sputter\$5 same undercut\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
14	41	((substrate or wafer or device or workpiece) same (barrier or layer or coat\$4 or film or form\$3 or deposit\$3) same ((poly near5 phenol\$4) or novolac or (poly\$5 near14 hydroxy near5 styrene))) and (resist or photoresist or photosensitive) and (expos\$4 or irradiat\$4 or illuminat\$4) and develop\$4 and (etch\$4 or remov\$4) and (plat\$4 or electroplat\$4) and undercut	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
15	53	430/311.ccls. and ((substrate or wafer or device or workpiece) same (barrier or layer or coat\$4 or film or form\$3 or deposit\$3) same ((poly near5 phenol\$4) or novolac or (poly\$5 near14 hydroxy near5 styrene))) and (resist or photoresist or photosensitive) and (expos\$4 or irradiat\$4 or illuminat\$4) and develop\$4 and (etch\$4 or remov\$4) and (plat\$4 or electroplat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
16	15	430/313.ccls. and ((substrate or wafer or device or workpiece) same (barrier or layer or coat\$4 or film or form\$3 or deposit\$3) same ((poly near5 phenol\$4) or novolac or (poly\$5 near14 hydroxy near5 styrene))) and (resist or photoresist or photosensitive) and (expos\$4 or irradiat\$4 or illuminat\$4) and develop\$4 and (etch\$4 or remov\$4) and undercut\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
17	1	"430"/\$.ccls. and ((substrate or wafer) same (barrier or layer or coat\$4 or film) same ((polyphenol\$4 near6 polymer\$4) or novolac) same (resist or photoresist or photosensitive)) and (expos\$4 or irradiat\$4 or illuminat\$4) and develop\$4 and (etch\$4 or remov\$4) and (plat\$4 or electroplat\$4) and (phenolic same (monomer\$5 near9 unit)) and undercut\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB